

AMENDMENTS TO THE CLAIMS

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Claim 1 (canceled)

Claim 2 (previously presented): The imaging device of claim 7, wherein said photosensitive elements are arranged in a two-dimensional array.

Claim 3 (currently amended): The imaging device of claim 7, wherein said transparent ~~plastic~~ material includes injection molded epoxy resin.

**β** Claim 4 (currently amended): The imaging device of claim 7, further comprising leads connected to said semiconductor chip, said leads being partially encapsulated in said transparent ~~plastic~~ material.

Claims 5-6 (canceled)

Claim 7 (currently amended): An imaging device, comprising:

a frame having a support structure, said support structure supporting a semiconductor chip;

said semiconductor chip having;

~~a package formed of transparent plastic material;~~

~~a semiconductor chip encapsulated within said package, said chip including an array of photosensitive elements for receiving an image and for generating corresponding signals, said photosensitive elements being covered by said transparent plastic material; and~~

said frame, support structure, and semiconductor chip encapsulated in a transparent material, said transparent material having an optical light transmitting device covering said photosensitive elements of said semiconductor chip.

Claim 8 (currently amended): The imaging device of claim 7, wherein said optical light transmitting device is formed of said transparent ~~plastic~~ material.

Claim 9 (currently amended): The imaging device of claim 7 wherein said optical light transmitting device is a color filter, said filter being formed of said transparent ~~plastic~~ material.

Claim 10 (currently amended): The imaging device of claim 7, further comprising a color filter array molded into said transparent ~~plastic~~ material.

Claim 11 (currently amended): An imaging system, comprising:

a system for transmitting an image including an image source and a first semiconductor device,

31. said image source capable of simultaneously transmitting an image to a plurality of semiconductor devices;

wherein said plurality of semiconductor devices includes first, second and third semiconductor devices on respective frames, each of said frames having a support structure, said first, second, and third semiconductor devices for receiving the said image and for generating corresponding signals; and wherein each of said frame, support structure, and respective semiconductor device is encapsulated in respective first, second and third packages for protecting and supporting each said first, second and third semiconductor devices ~~device~~, said packages being formed of transparent ~~plastic~~ material, said transparent plastic material including injection molded resin for transmitting an image from said image source onto said first, second and third semiconductor devices.

Claim 12 (original): The system of claim 11, wherein said image source includes a lens.

Claim 13 (previously presented): The system of claim 11 wherein said first, second and third semiconductor devices include complementary color filters.

Claim 14 (original): The system of claim 13, wherein said complementary color filters are molded into said first, second and third packages.

Claim 15 (currently amended): The ~~stem~~ system of claim 13, wherein said first, second and third packages include red, green and blue filters.

Claim 16 (original): The system of claim 13, wherein said first, second and third packages include cyan, magenta and yellow filters.

Claims 17-27 (canceled)

Claim 28 (currently amended): An imaging device, comprising:

~~a package formed of a housing, wherein said housing is formed of a ceramic material, and a transparent plastic cover;~~ having a cavity and a bottom surface;

~~a semiconductor chip located within said package~~ cavity of said housing, said semiconductor; ~~said chip~~ including an array of photosensitive elements for receiving an image and for generating corresponding signals, said photosensitive elements being covered by ~~said a transparent plastic cover;~~

said semiconductor chip being encapsulated in a transparent material, wherein said transparent material has an uppermost surface substantially planar to an uppermost surface of said housing; and

an optical light transmitting device covering said photosensitive elements.

Claim 29 (currently amended): The imaging device of claim 28, wherein said transparent ~~plastic~~ cover includes a color filter.

Claim 30 (canceled)

Claim 31 (currently amended): The imaging device of claim 28, wherein said housing is formed of molded plastic.

Claim 32 (currently amended): The imaging device of claim 7, wherein said optical light transmitting device is a lens, said lens being formed of said transparent plastic material.

bl Claim 33 (new): The imaging device of claim 28, wherein said housing is formed of a ceramic material.

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